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08-17-1999

Y. DOCKET NO: M-7279 US

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

REC



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

(a) Bo Tao

(b)

(c)

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):

Name: Sony Corporation

Internal Address: _____

Street Address: 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku,
Tokyo, Japan

10525 U.S. PTO
09/370065
08/06/99

3. Nature of Conveyance:

Assignment Merger

Security Agreement Change of Name

Other _____

Execution Date: July 27, 1999

Name and address of receiving party(ies):

Name: Sony Electronics Inc.

Internal Address: _____

Street Address: 1 Sony Drive, Park Ridge, New Jersey, 07656

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: June 18, 1999

A. Patent Application No.(s) -Unknown

Title: A Deadzone Quantization Method And Apparatus For Image Compression

B. Patent No.(s)
09/370065

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David W. Heid

Internal Address: SKJERVEN, MORRILL, MacPHERSON,
FRANKLIN & FRIEL LLP

Street Address: 25 METRO DRIVE, SUITE 700

City SAN JOSE State CA ZIP 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

Authorized to be charged to Deposit Account 19-2386

Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

08/16/1999 MTHAI1 00000337 192386 09370065
01 FC:581 (40.00 CH)

DO NOT USE THIS SPACE

8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Heid, Esq. Reg. #25,875 David W. Heid 8/06/99
Name of Person Signing Signature Date

Total number of pages comprising cover sheet: 3

EXPRESS MAIL LABEL NO.: EL 375 479 040 US

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **A Deadzone Quantization Method And Apparatus For Image Compression** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony Electronics Inc. a Delaware corporation with offices at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

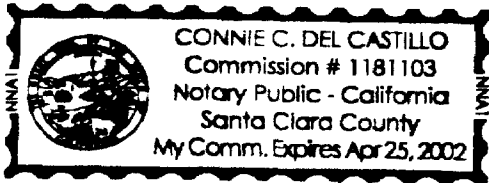
Bo Tao 6/18/99
Name of first inventor Execution date of U.S. Patent Application

Sunnyvale, California
Residence of first or sole inventor

Bo Tao 7/27/99
Signature of first or sole inventor Date of this assignment

State of California,
County of Santa Clara ss.

On this 27 day of July in the year of 1999, the undersigned notary public, personally appeared the above-named assignor, known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged execution of this instrument.



WITNESS my hand and official seal.

Connie C. del Castillo

SIGNATURE OF NOTARY